

SIPMOS® Small-Signal-Transistor

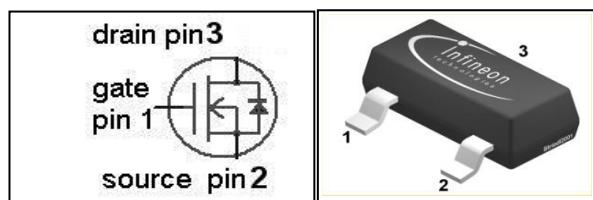
Features

- N-channel
- Depletion mode
- dv/dt rated
- Available with $V_{GS(th)}$ indicator on reel
- Pb-free lead-plating; RoHS compliant
- Halogen-free according to AEC61249-2-21
- Qualified according to AEC Q101

Product Summary

V_{DS}	100	V
$R_{DS(on),max}$	12	Ω
$I_{DSS,min}$	0.09	A

PG-SOT-23



Halogen-Free

Type	Package	Pb-free	Tape and Reel Information	Marking
BSS169	PG-SOT-23	Yes	H6327: 3000 pcs/reel	SFs
BSS169	PG-SOT-23	Yes	H6906: 3000 pcs/reel sorted in $V_{GS(th)}$ bands ¹⁾	SFs

Maximum ratings, at $T_j=25$ °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$T_A=25$ °C	0.17	A
		$T_A=70$ °C	0.14	
Pulsed drain current	$I_{D,pulse}$	$T_A=25$ °C	0.68	
Reverse diode dv/dt	dv/dt	$I_D=0.19$ A, $V_{DS}=20$ V, $di/dt=200$ A/ μ s, $T_{j,max}=150$ °C	6	kV/ μ s
Gate source voltage	V_{GS}		± 20	V
ESD Class		JESD22-A114-HBM	Class 0	
Power dissipation	P_{tot}	$T_A=25$ °C	0.36	W
Operating and storage temperature	T_j, T_{stg}		-55 ... 150	°C
IEC climatic category; DIN IEC 68-1			55/150/56	

¹⁾ see table on next page and diagram 11

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Thermal characteristics

Thermal resistance, junction - ambient	R_{thJA}	minimal footprint	-	-	250	K/W
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Electrical characteristics, at $T_j=25$ °C, unless otherwise specified

Static characteristics

Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=-10$ V, $I_D=250$ µA	100	-	-	V
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=3$ V, $I_D=50$ µA	-2.9	-2.2	-1.8	
Drain-source cutoff current	$I_{\text{D}(\text{off})}$	$V_{\text{DS}}=100$ V, $V_{\text{GS}}=-10$ V, $T_j=25$ °C	-	-	0.1	µA
		$V_{\text{DS}}=100$ V, $V_{\text{GS}}=-10$ V, $T_j=125$ °C	-	-	10	
Gate-source leakage current	I_{GSS}	$V_{\text{GS}}=20$ V, $V_{\text{DS}}=0$ V	-	-	10	nA
On-state drain current	I_{DSS}	$V_{\text{GS}}=0$ V, $V_{\text{DS}}=10$ V	90	-	-	mA
Drain-source on-state resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=0$ V, $I_D=0.05$ A	-	5.3	12	Ω
		$V_{\text{GS}}=10$ V, $I_D=0.19$ A	-	2.9		
Transconductance	g_{fs}	$ V_{\text{DS}} >2 I_D R_{\text{DS}(\text{on})\text{max}},$ $I_D=0.15$ A		0.20	-	s

Threshold voltage $V_{\text{GS}(\text{th})}$ sorted in bands²⁾

J	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=3$ V, $I_D=50$ µA	-2	-	-1.8	V
K			-2.15	-	-1.95	
L			-2.3	-	-2.1	
M			-2.45	-	-2.25	
N			-2.6	-	-2.4	

²⁾ Each reel contains transistors out of one band whose identifying letter is printed on the reel label. A specific band cannot be ordered separately.

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic characteristics

Input capacitance	C_{iss}	$V_{GS}=-10\text{ V}, V_{DS}=25\text{ V}, f=1\text{ MHz}$	-	51	68	pF
Output capacitance	C_{oss}		-	9	13	
Reverse transfer capacitance	C_{rss}		-	4	7	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=50\text{ V}, V_{GS}=-3\text{...}7\text{ V}, I_D=0.12\text{ A}, R_{G,ext}=6\Omega$	-	2.9	4.2	ns
Rise time	t_r		-	2.7	4.0	
Turn-off delay time	$t_{d(off)}$		-	11	17	
Fall time	t_f		-	27	40	

Gate Charge Characteristics

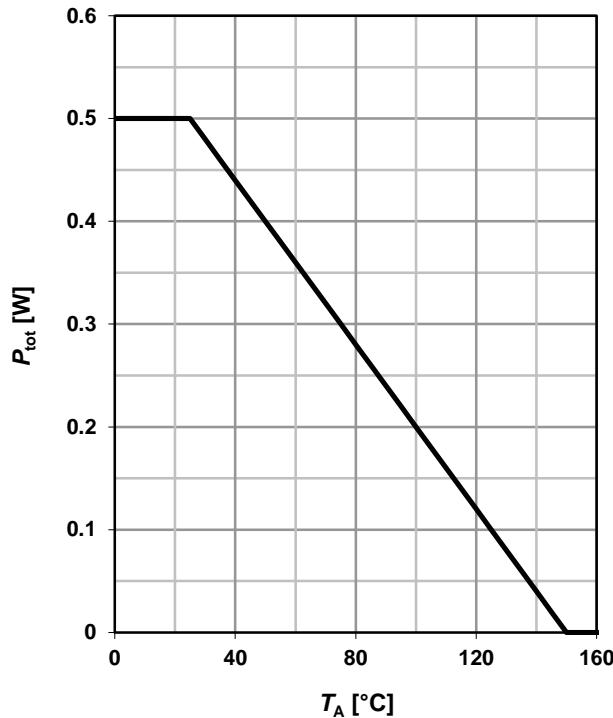
Gate to source charge	Q_{gs}	$V_{DD}=80\text{ V}, I_D=0.12\text{ A}, V_{GS}=-3\text{ to }7\text{ V}$	-	0.12	0.16	nC
Gate to drain charge	Q_{gd}		-	0.9	1.4	
Gate charge total	Q_g		-	2.1	2.8	
Gate plateau voltage	$V_{plateau}$		-	-0.43	-	V

Reverse Diode

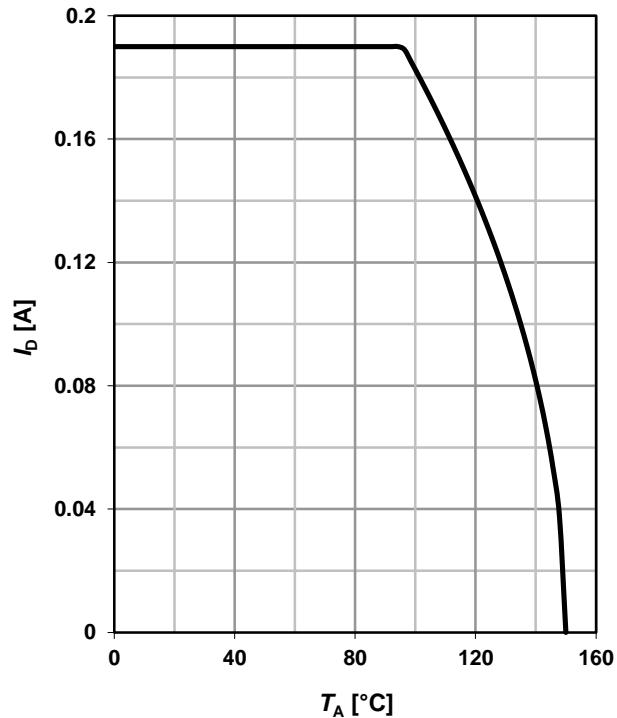
Diode continuous forward current	I_S	$T_A=25\text{ }^\circ\text{C}$	-	-	0.19	A
Diode pulse current	$I_{S,pulse}$		-	-	0.76	
Diode forward voltage	V_{SD}	$V_{GS}=-10\text{ V}, I_F=0.19\text{ A}, T_j=25\text{ }^\circ\text{C}$	-	0.82	1.2	V
Reverse recovery time	t_{rr}	$V_R=50\text{ V}, I_F=0.12\text{ A}, di_F/dt=100\text{ A}/\mu\text{s}$	-	20.5	25.6	ns
Reverse recovery charge	Q_{rr}		-	9.7	12.1	nC

1 Power dissipation

$$P_{\text{tot}} = f(T_A)$$

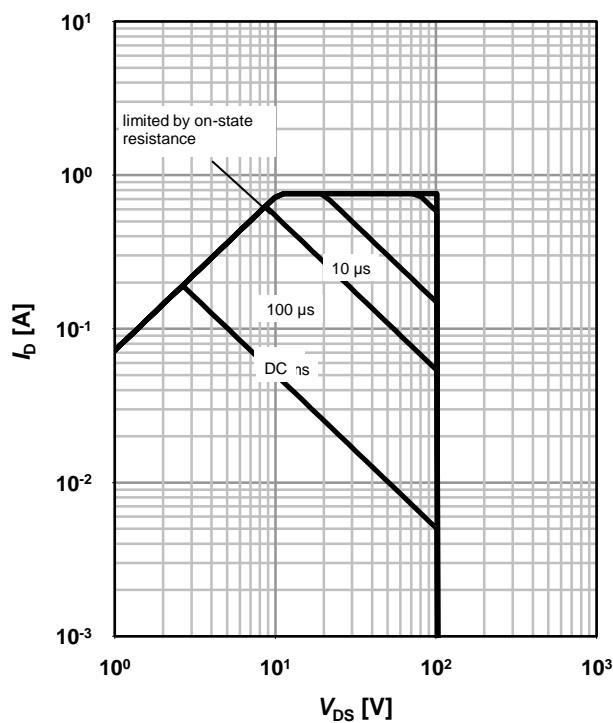

2 Drain current

$$I_D = f(T_A); V_{GS} \geq 10 \text{ V}$$


3 Safe operating area

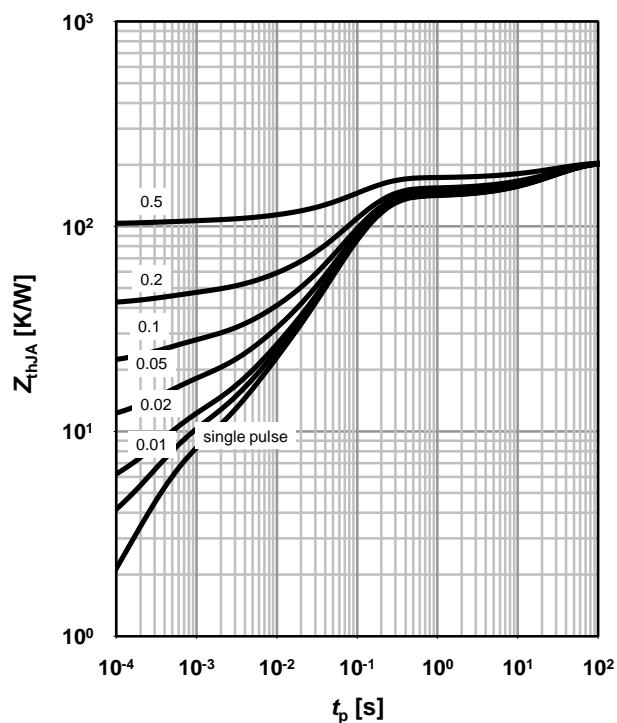
$$I_D = f(V_{DS}); T_A = 25 \text{ °C}; D = 0$$

parameter: t_p

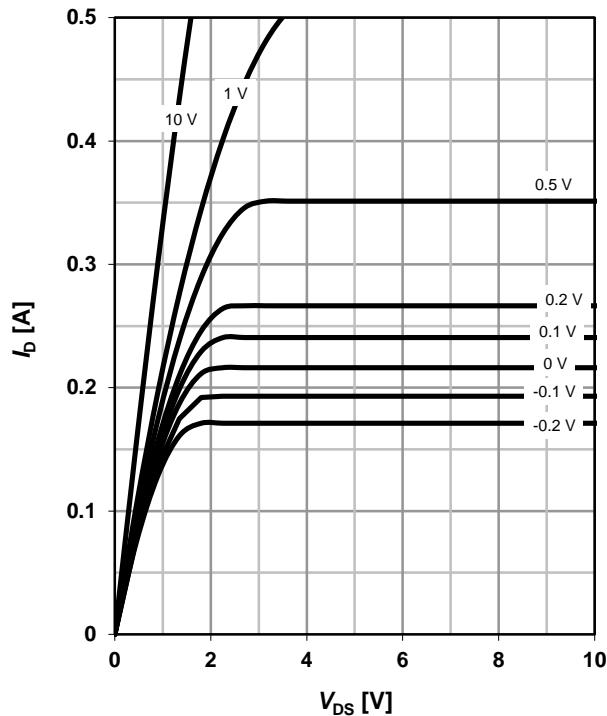

4 Max. transient thermal impedance

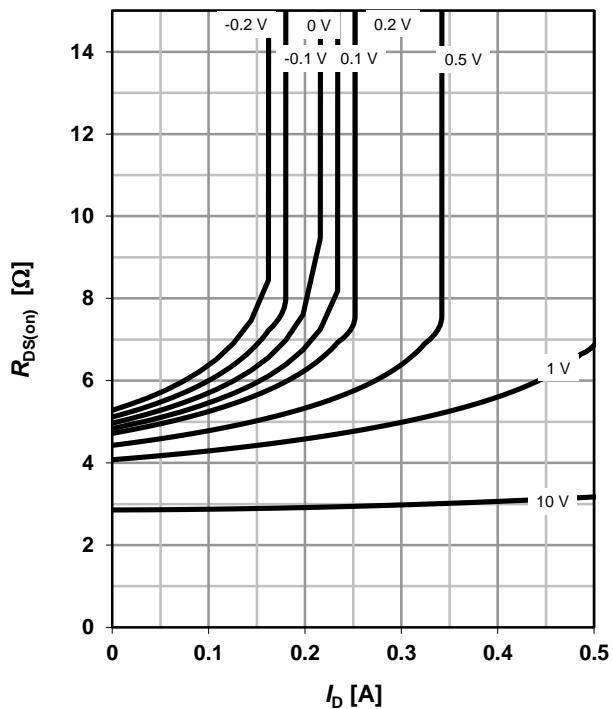
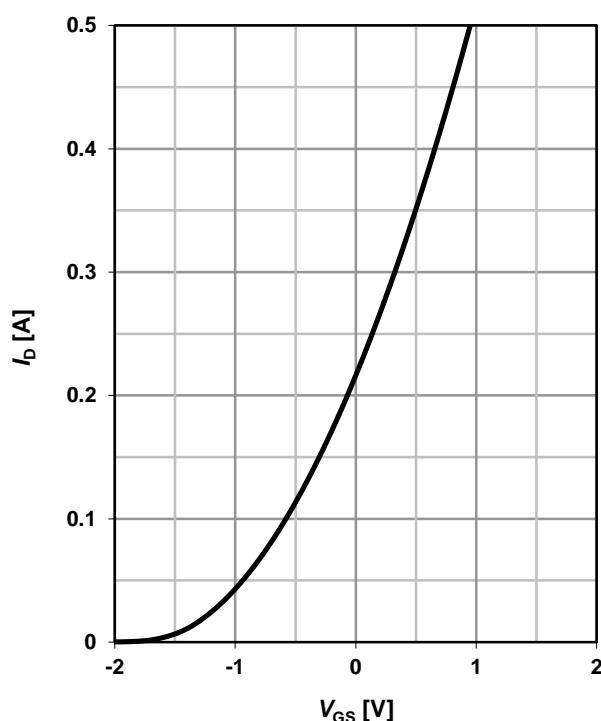
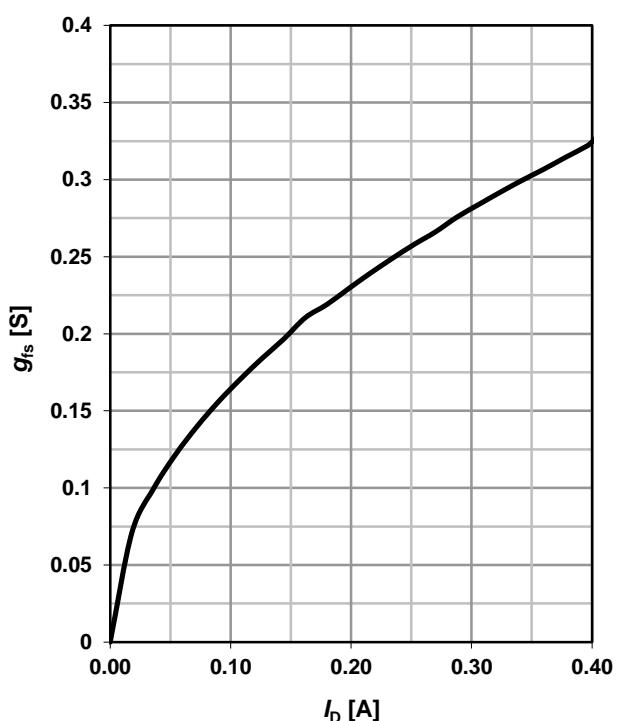
$$Z_{\text{thJA}} = f(t_p)$$

parameter: $D = t_p/T$



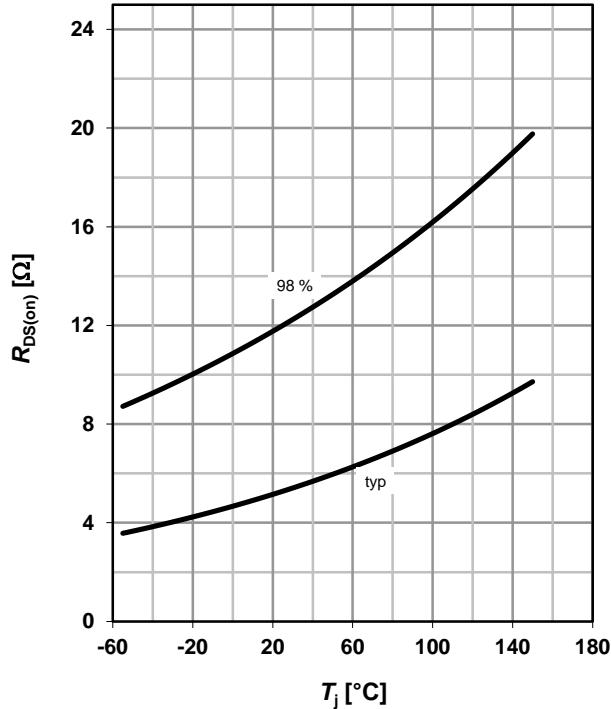
5 Typ. output characteristics
 $I_D=f(V_{DS})$; $T_j=25\text{ }^\circ\text{C}$

parameter: V_{GS}

6 Typ. drain-source on resistance
 $R_{DS(on)}=f(I_D)$; $T_j=25\text{ }^\circ\text{C}$

parameter: V_{GS}

7 Typ. transfer characteristics
 $I_D=f(V_{GS})$; $|V_{DS}|>2|I_D|R_{DS(on)max}$

8 Typ. forward transconductance
 $g_{fs}=f(I_D)$; $T_j=25\text{ }^\circ\text{C}$


9 Drain-source on-state resistance

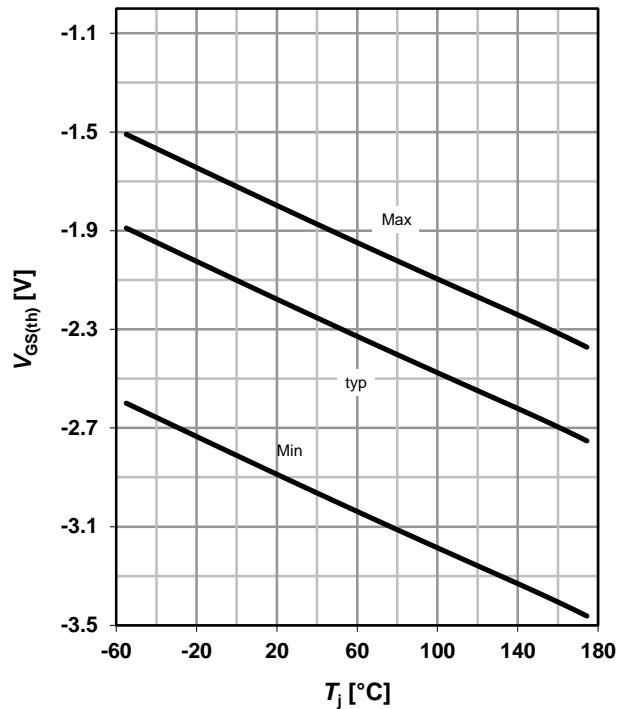
$R_{DS(on)}=f(T_j)$; $I_D=0.05 \text{ A}$; $V_{GS}=0 \text{ V}$



10 Typ. gate threshold voltage

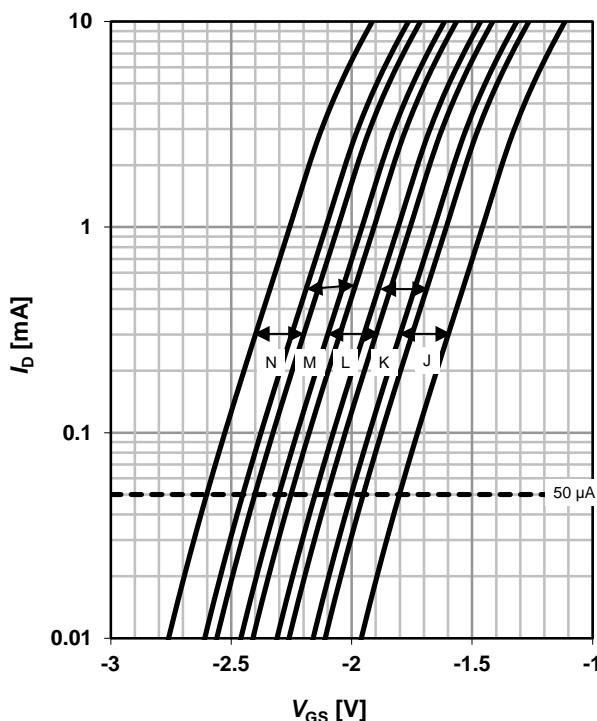
$V_{GS(th)}=f(T_j)$; $V_{DS}=3 \text{ V}$; $I_D=50 \mu\text{A}$

parameter: I_D



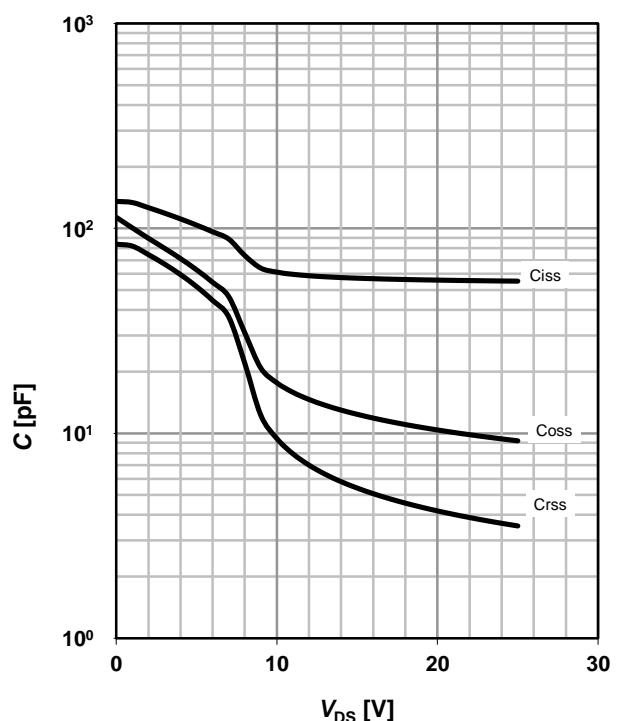
11 Threshold voltage bands

$I_D=f(V_{GS})$; $V_{DS}=3 \text{ V}$; $T_j=25 \text{ }^{\circ}\text{C}$



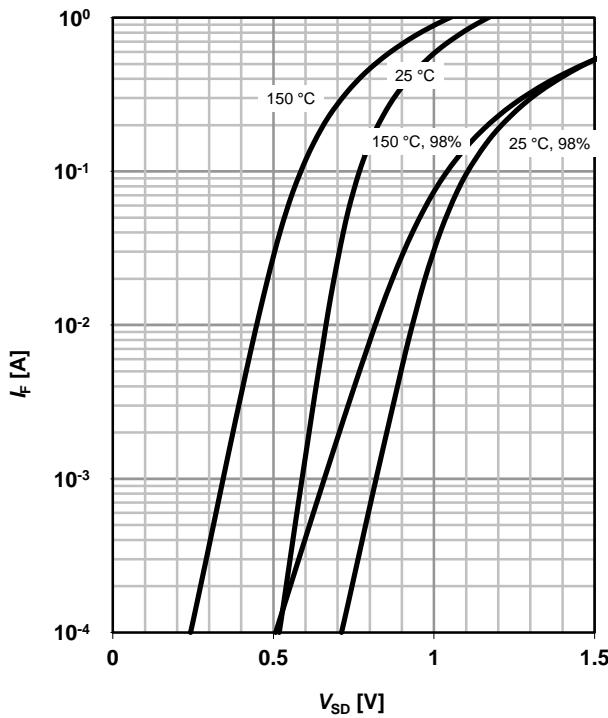
12 Typ. capacitances

$C=f(V_{DS})$; $V_{GS}=-10 \text{ V}$; $f=1 \text{ MHz}$

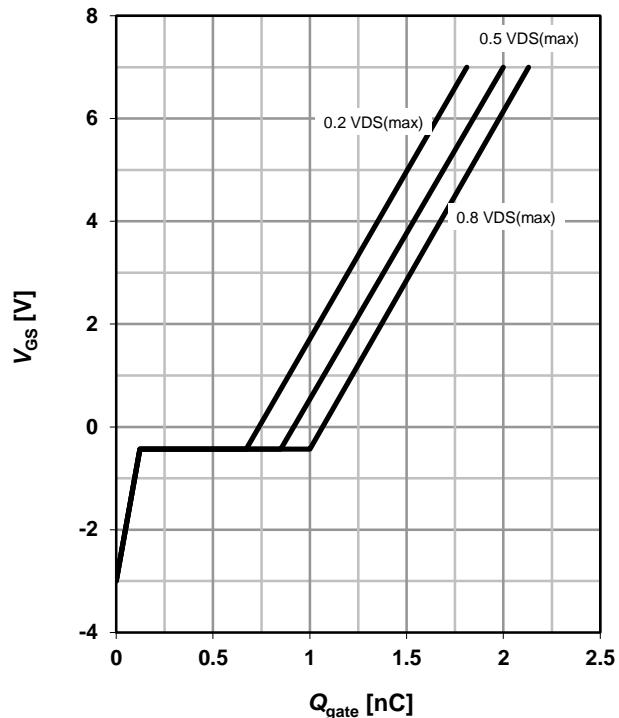


13 Forward characteristics of reverse diode

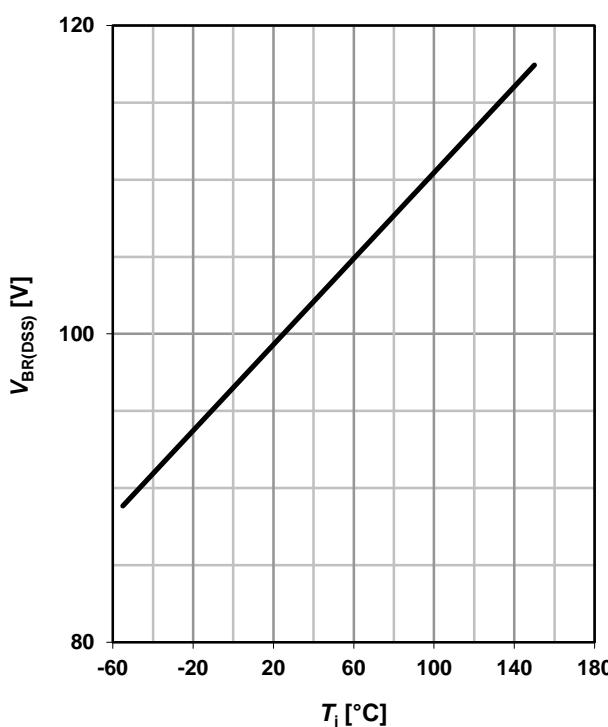
$$I_F = f(V_{SD})$$

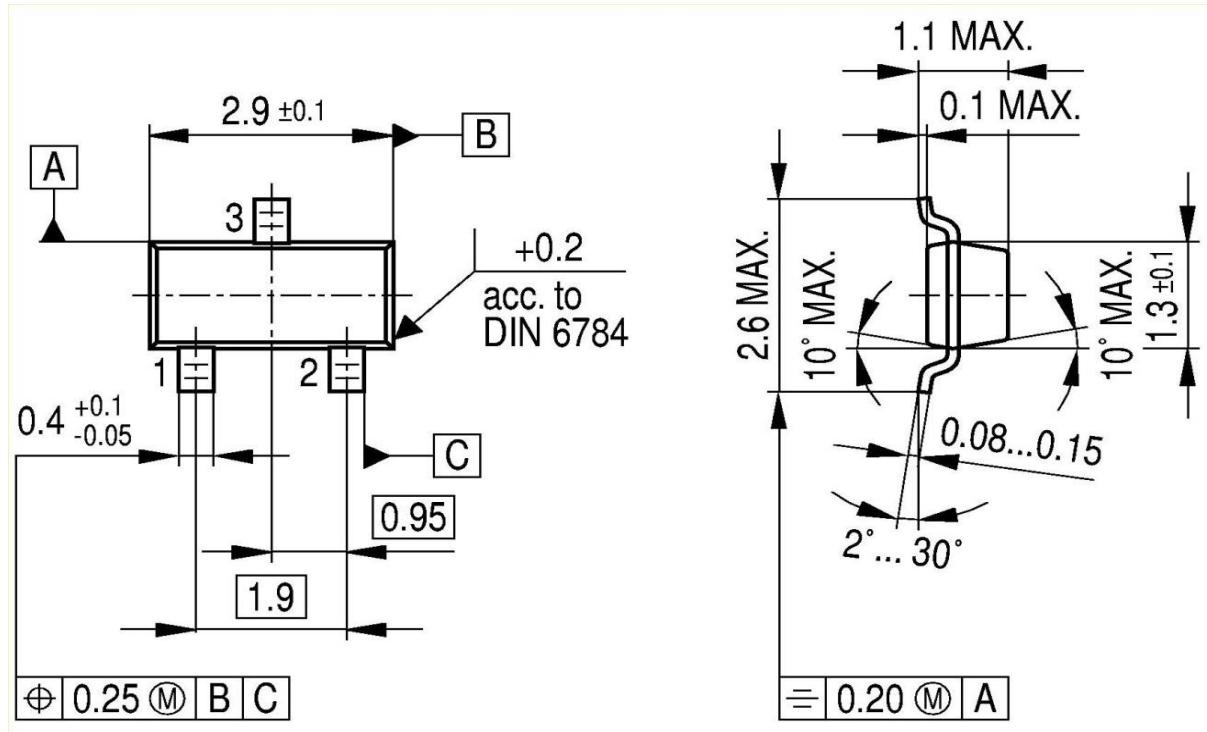
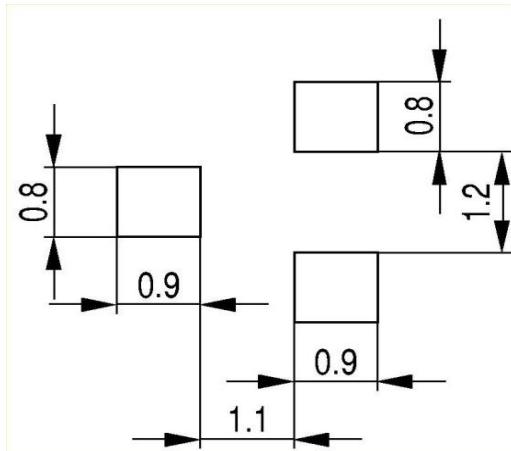
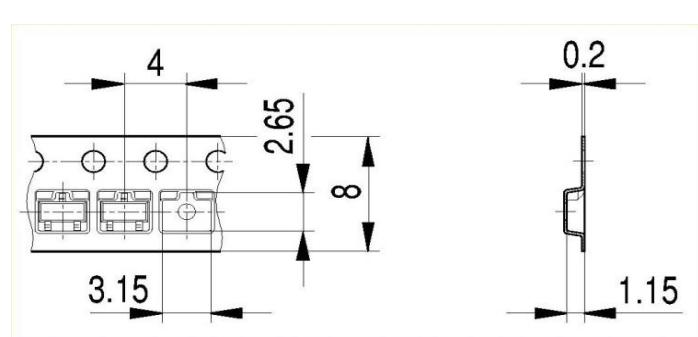
parameter: T_j

15 Typ. gate charge

$$V_{GS} = f(Q_{gate}); I_D = 0.12 \text{ A pulsed}$$

parameter: V_{DD}

16 Drain-source breakdown voltage

$$V_{BR(DSS)} = f(T_j); I_D = 250 \mu\text{A}$$



Package Outline:

Footprint:

Packaging:


Dimensions in mm